

Wi-Fi®/ Bluetooth® Modules

Wi-Fi® modules

Type 1FX

PN: LBWA1KL1FX-875

CYW43364 Chipset

6.95 x 5.15 x 1.1mm

FCC/IC/CE*/Japan Certified



802.11 b/g/n

Wi-Fi® + Bluetooth® modules



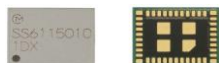
Type 1DX

PN: LBEE5KL1DX-883

CYW4343W Chipset

6.95 x 5.15 x 1.1 mm

FCC/IC/CE*/Japan Certified



802.11 b/g/n + Bluetooth® 4.2



Type 1LV

PN: LBEE59B1LV-278

CYW43012 Chipset

10.0 x 7.2 x 1.4 mm

FCC/IC/CE*/Japan Certified



802.11 a/b/g/n/ac + Bluetooth® 5.0
(It only supports 20MHz channel bandwidth)



Type 1MW

PN: LBEH5HY1MW-230

CYW43455 Chipset

7.9 x 7.3 x 1.1 mm

FCC/IC/CE*/Japan Certified



802.11 a/b/g/n/ac + Bluetooth® 5.0

Type 1CX

PN: LBEH5UL1CX-887

CYW4356 Chipset

11.5 x 8.8 x 1.0 mm



802.11 a/b/g/n/ac + Bluetooth® 5.0

MIMO



Type 1VA

PN: LBEE5XV1VA-495

CYW88359 Chipset

11.4 x 8.9 x 1.4 mm

FCC/IC/CE*/Japan Certified



802.11 a/b/g/n/ac + Bluetooth® 4.2

MIMO
RSDB

*Conducted results for CE Marking Conformity Assessment Procedures are available

Wi-Fi® MCU Modules

ElectricImp modules

electric imp

☁ Type 1GC/imp005

PN: LBWA1UZ1GC-958
PN: LBWA1UZ1GC-901 (Imp005)
CYW43907 Chipset
10.0 x 10.0 x 1.3 mm

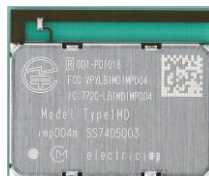


WICED, ElectricImp
FCC/IC/CE* Reference Certified

📶 802.11 a/b/g/n
+ Ethernet + ARM Cortex- R4

☁ Type 1MD/imp004m

PN: LBEE5ZZ1MD-011
CYW43438+STM Chipset
21.0 x 17.5 x 2.3 mm

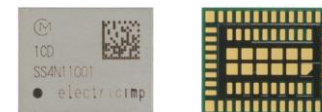


ElectricImp
FCC/IC/CE*/Japan Certified

📶 802.11 b/g/n + Bluetooth® 4.1
+ ARM Cortex- M4

☁ Type 1CD/imp003

PN:LBWA1ZV1CD-716
CYW43362+STM Chipset
10.0 x 7.9 x 1.25 mm



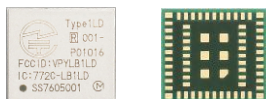
ElectricImp
FCC/IC/CE* Reference Certified

📶 802.11 b/g/n
+ ARM Cortex-M4

Ayla modules

☁ Type 1LD

PN: LBEE5PA1LD-005
PN: LBEE5PA1LD-222(Ayla)
CYW43438+STM Chipset
8.9 x 7.8 x 1.2 mm



WICED, Ayla
FCC/IC/CE */Japan Certified

📶 802.11 b/g/n + Bluetooth® 4.2
+ ARM Cortex-M4

☁ Type 1AD

PN: LBWA1CS1AD-806
CYW4390 Chipset
9.4 x 8.9 x 1.2 mm



Ayla
FCC/IC/CE* Reference Certified

📶 802.11 b/g/n
+ ARM Cortex-M3

 **Ayla Networks**

Wi-Fi® MCU Modules

Wi-Fi/BT MCU modules

Type 1QP

PN: LBEE5WQ1QP-276

CYW43907+CYW20707 Chipset
11.0 x 11.0 x 1.2 mm



WICED

 **802.11 a/b/g/n + Bluetooth® 5.0**
+ ARM Cortex- R4

Type 1QX

PN: LBEE5WQ1QX-277

CYW54907+CYW20707 Chipset
11.0 x 11.0 x 1.2 mm



WICED

 **802.11 a/b/g/n + Bluetooth® 5.0**
+ ARM Cortex- R4

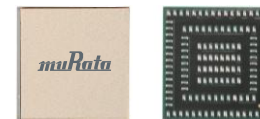
Wi-Fi MCU modules



Type 1PS

PN: LBWA1UZ1PS-241

CYW54907 Chipset
10.0 x 10.0 x 1.3 mm



WICED

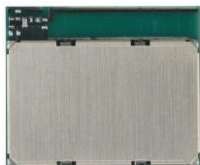
 **802.11 a/b/g/n/ac**
+ Ethernet + ARM Cortex- R4



Type 1HD

PN: LBWA1ZZ1HD-004

CYW43438+STM Chipset
21.0 x 17.5 x 2.3 mm



WICED

FCC/IC/CE*/Japan Certified

 **802.11 b/g/n**
+ ARM Cortex- M4



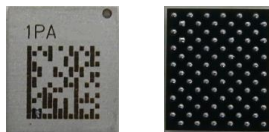
Bluetooth®/ BLE/ 802.15.4 Modules

Type 1PA

PN: LBCA1KU1PA-245

CYW20719 Chipset

5.9 x 5.1 x 1.17mm



Bluetooth/BLE
WICED Studio

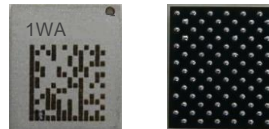
Bluetooth® 5.0

Type 1WA

PN: LBCA1KU1WA

CYW20721 Chipset

5.9 x 5.1 x 1.17mm



Bluetooth/BLE
WICED Studio

Bluetooth® 5.0

Type 1GR

PN: LBCA1ZZ1GR-084

CYW20736 chipset

9.0 x 7.0 x 1.2mm



BLE
WICED Studio
FCC/IC/CE*/Japan Certified

Bluetooth® 4.1



*Conducted results for CE Marking Conformity Assessment Procedures are available

Wi-Fi®/ Bluetooth® Modules

Wi-Fi® + Bluetooth® MCU modules

Type 1JP/1JQ

PN: LBWA1ZZ1JP-928

PN: LBWA1ZZ1JQ-171

TI CC3100/CC3200

Chipset

13.2 x 21.45 x 2.65mm



SimpleLink SDK

802.11 b/g/n

+ ARM Cortex- M3

FCC/IC/CE*/Japan Certified

Type 1KP/1KQ/1KR/1KS

PN: LBWA1ZZ1KP-289

PN: LBWA1ZZ1KQ-290

PN: LBWA1ZZ1KR-291

PN: LBWA1ZZ1KS-088

TI CC3120/CC3220

CC3220S/CC3220SF

13.2 x 21.45 x 2.65mm



SimpleLink Gen2 SDK

802.11 b/g/n

+ ARM Cortex- M3

FCC/IC/CE*/Japan Certified

Wi-Fi® + Bluetooth® modules

Type WT

PN: LBEP5CLWTC-631

WL1801/1831 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 75°C



802.11 b/g/n + Bluetooth® 4.1

Type WM

PN: LBEP5CLWMC-633

WL1803/1833 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 75°C



802.11 a/b/g/n + Bluetooth® 4.1

Japan Certified

Type XR

PN: LBEP5CLXRC-701

WL1801 Chipset

9.9 x 8.8 x 1.3 mm

-40 ~ 85°C



802.11 b/g/n